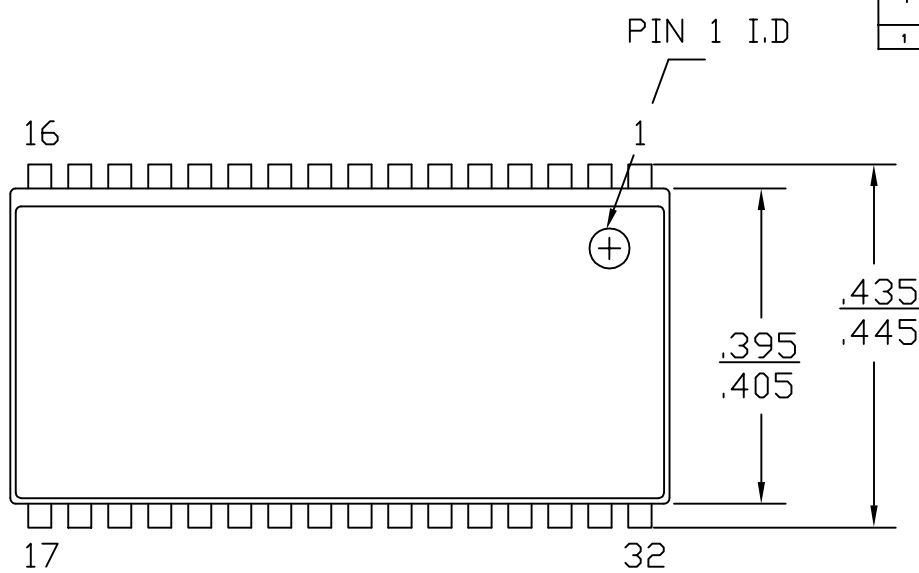
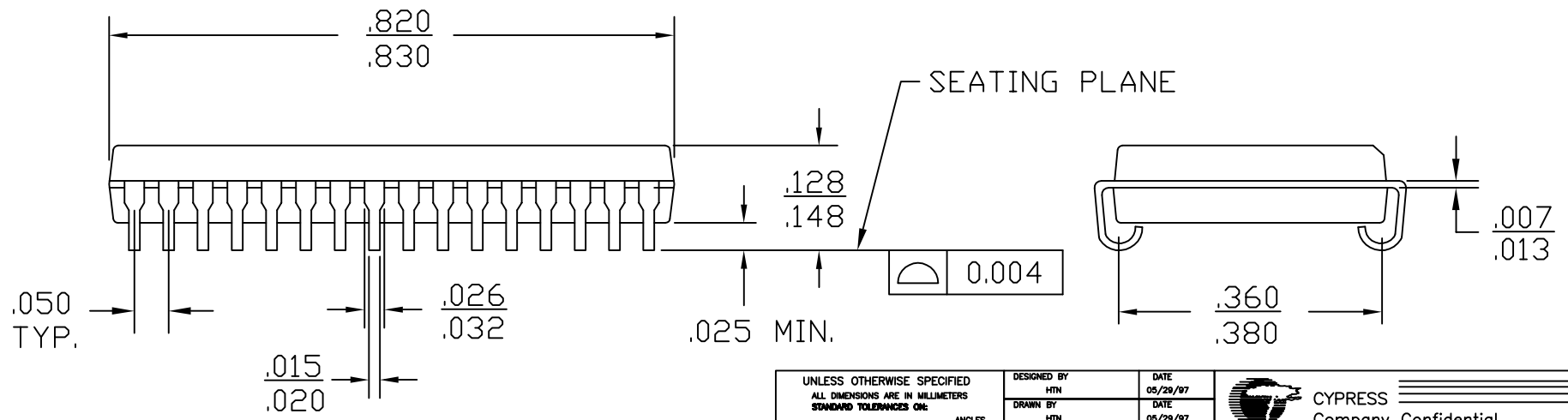


32 Lead (400 MIL) Molded SOJ V33


REVISIONS						
PAGE	ZONE	REV	ECN	DESCRIPTION	DATE	APPROVED
1	-	**	N/A	N/A	N/A	N/A
1	-	*A	49390	CHG. TITLE	05/29/97	N/A
1	-	*B	59367	REMOVE DETAIL "A"	12/29/98	N/A
1	-	*C	2871406	Changed template, & title from 32LD (400 MIL) SOJ PKG OUTLINE to PACKAGE OUTLINE, 32L SOJ 400 MILS V32.4 (MOLDED SOJ V33).	02/02/10	QAD
1	-	*D	3146953	ECN SUNSET NO CHANGE	01/19/11	QAD



DIMENSIONS IN INCHES MIN. MAX.



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UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN MILLIMETERS STANDARD TOLERANCES ARE:		DESIGNED BY HTM	DATE 05/29/97	 CYPRESS Company Confidential	
DECIMALS .XX ± 0.05	ANGLES ± 1°	DRAWN BY HTM	DATE 05/29/97		
.XXX ±		CHECKED BY TSV	DATE 02/02/10	TITLE PACKAGE OUTLINE, 32L SOJ 400 MILS V32.4 (MOLDED SOJ V33)	
.XXXX ±		APPROVED BY QAD	DATE 02/02/10		
MATERIAL N/A		APPROVED BY JGUA	DATE 02/02/10	SIZE A	PART NO. V32.4
FINISH N/A		APPROVED BY N/A	DATE N/A	DWG NO 51-85033	REV *D
		SCALED TO FIT N/A		SHEET 1 OF 1	